

ABSTRACT

An object of the present invention is to provide a resin composition that is curable at low temperatures around room temperature in a relatively short time (within
5 several hours), and is not prone to produce contamination on the surroundings caused by resin volatilization, and that is suitable as a one-part adhesive for use in the manufacture of an image sensor module or an electronic component. The resin composition of the present invention contains a 2-methylene-1,3-dicarbonyl compound and an initiator. The 2-methylene-1,3-dicarbonyl compound has a
10 molecular weight of 180 to 10,000, and the initiator contains a basic substance having a pK_a of 8 or greater. Further, the 2-methylene-1,3-dicarbonyl compound is a compound containing a structural unit represented by formula (I) below.

